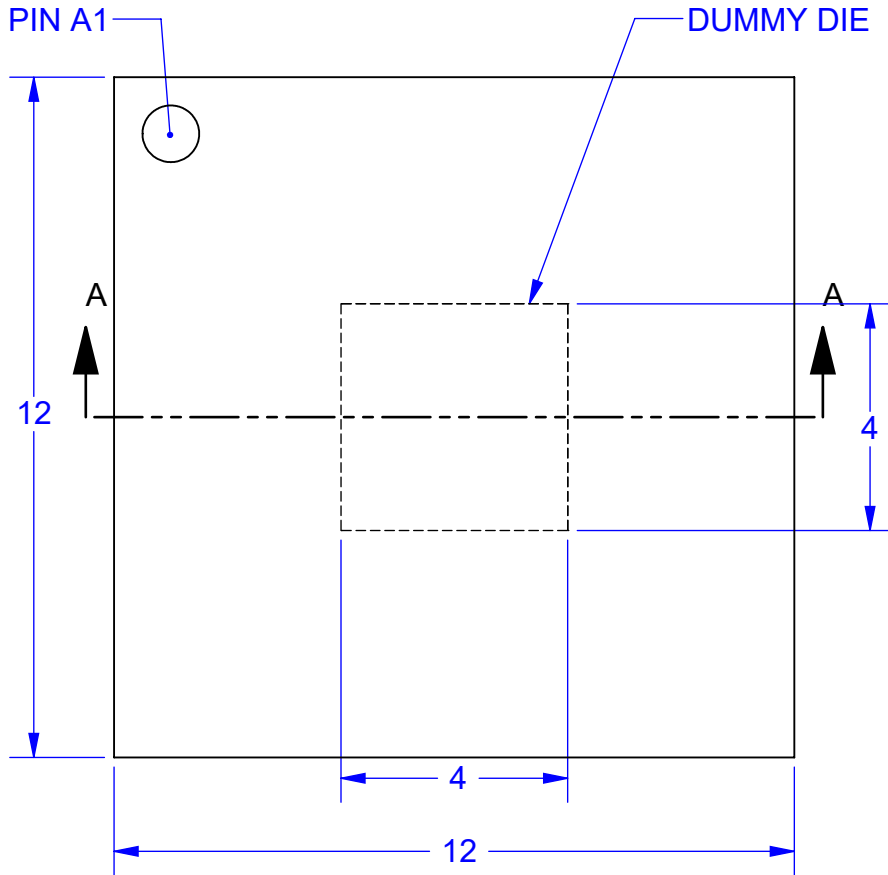
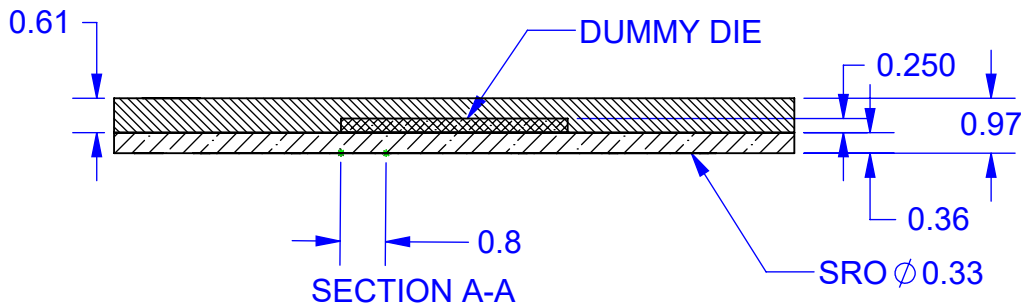
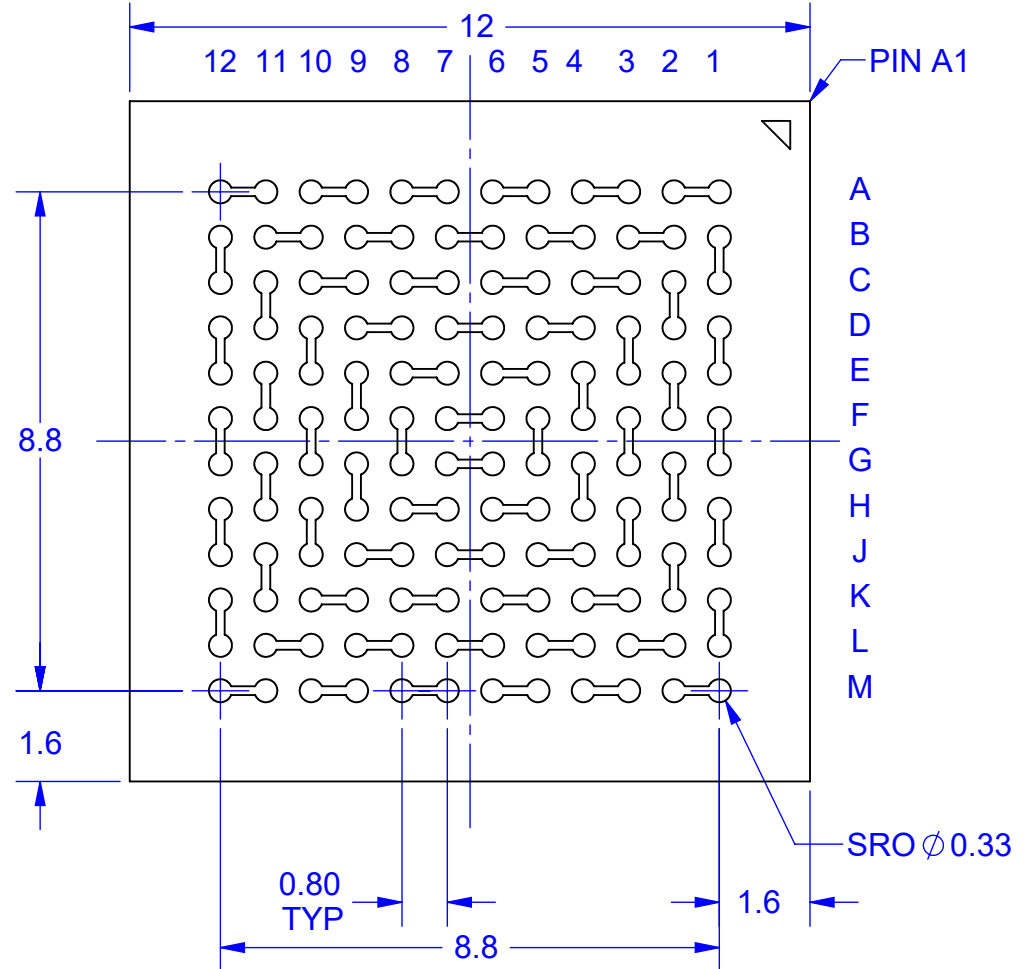


TOP VIEW



PAD VIEW

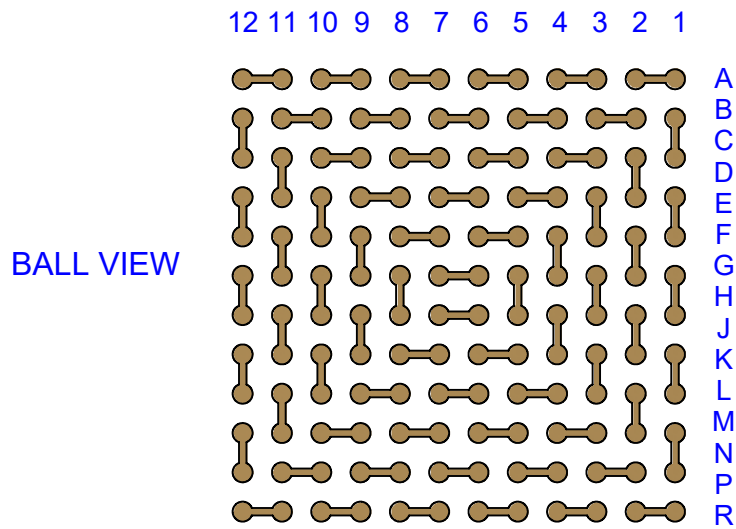


Notes: (Unless Otherwise Specified).

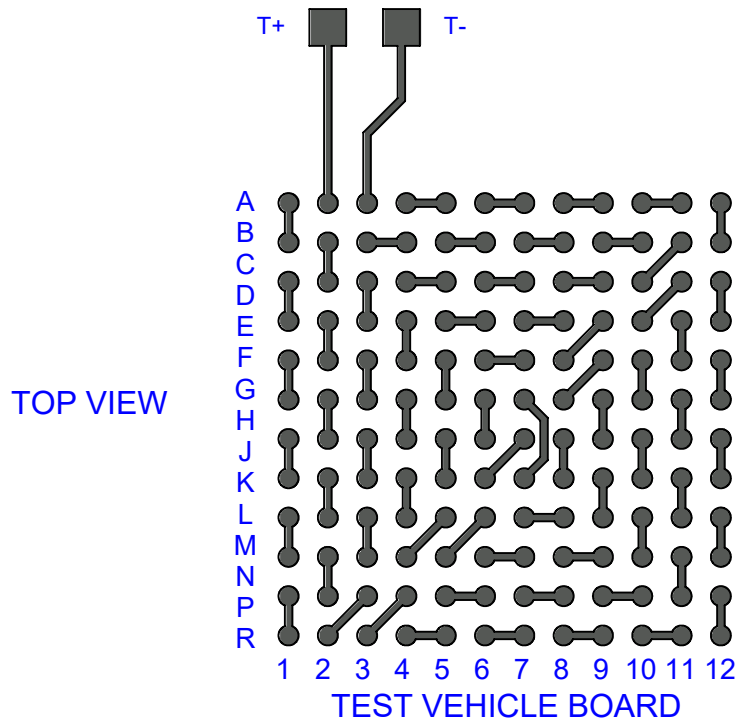
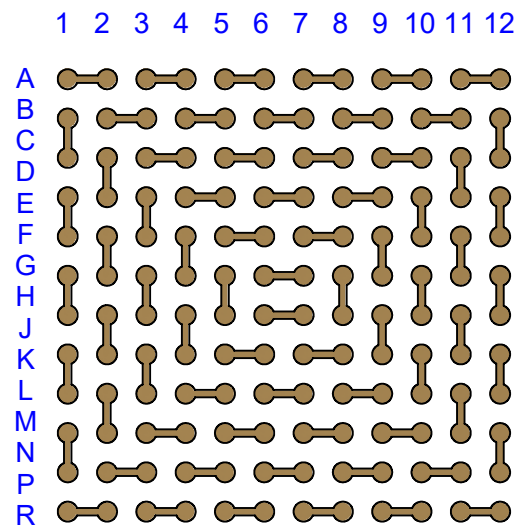
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.406mm (16 mil).
- 4) SOLDER MASK DEFINED PAD OPENING: 0.33mm (13 mil).
- 5) PAD MATERIAL: CU / Ni / Au.
- 6) SUBSTRATE MATERIAL: BT.
- 7) DUMMY DIE: SIZE OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
LGA144T.8G-DC128	NONE	YES	YES	YES

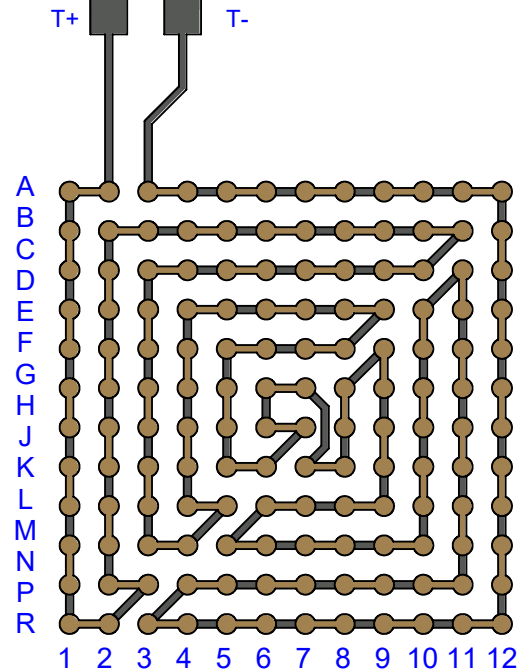
TOLERANCE UNLESS NOTED		APPROVALS		DATE						
X.X	+/- 0.1	DRAWN J. Hines		5/25/2011						TITLE LGA144T.8G-DC128 DAISY CHAIN DUMMY
X.XX	+/- 0.05	ENG				SCALE 7.5:1				
X.XXX	+/- 0.025	MFG				SIZE A		DRAWING NO. 581288		REV A
ANGLES +/- 0.5°		QA				DO NOT SCALE DRAWING				
ALL DIMENSIONS IN		CUST				SHEET 1 OF 3				
<input type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS		REVISED								



BOTTOM SIDE
(TOP X-RAY VIEW)



AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



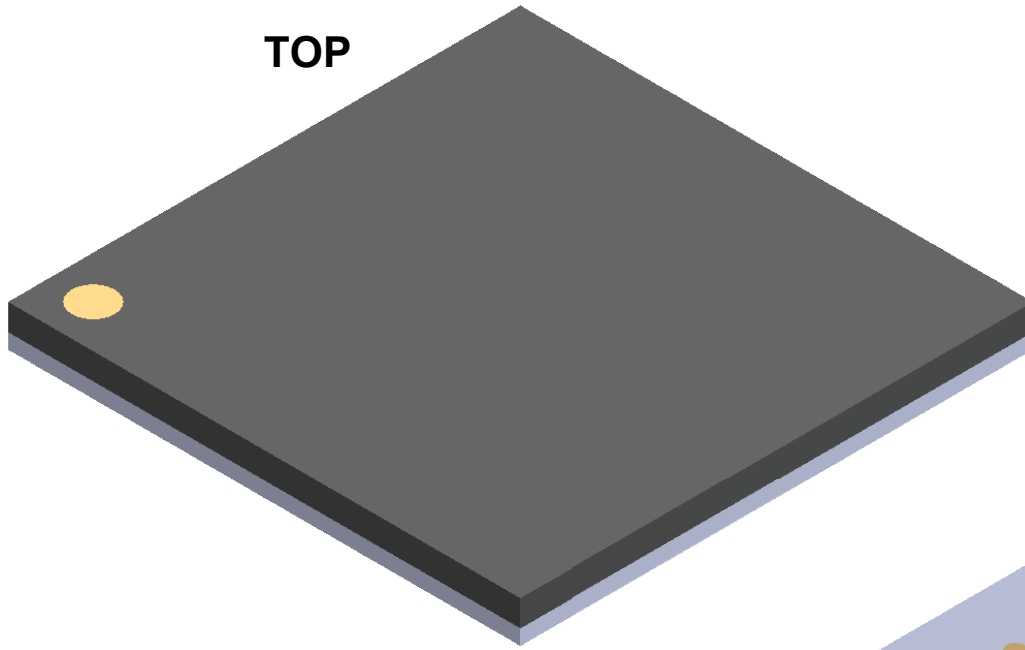
Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.406mm (16mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm (6mil).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.33mm (13mil).

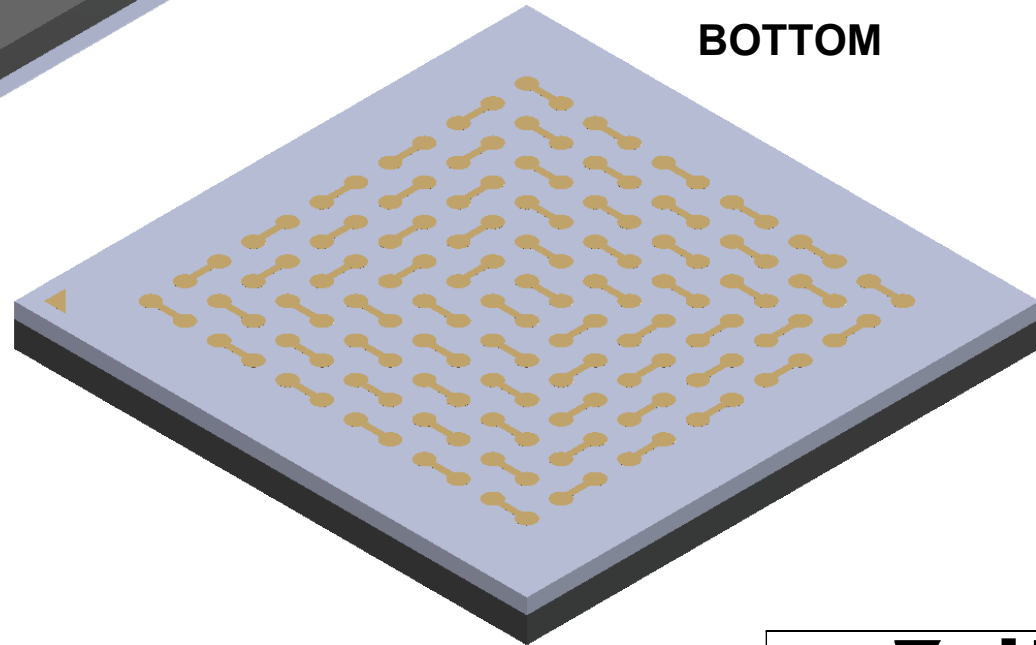
TopLine [®]			
TITLE		LGA144T.8G-DC128 DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
6.5:1	A	581288	A
DO NOT SCALE DRAWING			SHEET 2 OF 3

MODEL

TOP



BOTTOM



TopLine[®]

TITLE				LGA144T.8G-DC128 DAISY CHAIN DUMMY			
SCALE	SIZE	DRAWING NO.		REV			
5:1	A	581288		A			
DO NOT SCALE DRAWING			SHEET 3 OF 3				